

FPF2116

IntelliMAX™ Advanced Load Management Products

Features

- 1.8 to 5.5V Input Voltage Range
- Controlled Turn-On
- 200mA Current Limit
- Undervoltage Lockout
- Thermal Shutdown
- <2μA Shutdown Current
- Auto Restart
- Fast Current limit Response Time
 - 3μs to Moderate Over Currents
 - 20ns to Hard Shorts
- Fault Blanking
- Reverse Current Blocking
- RoHS Compliant

Applications

- PDAs
- Cell Phones
- GPS Devices
- MP3 Players
- Digital Cameras
- Peripheral Ports
- Hot Swap Supplies



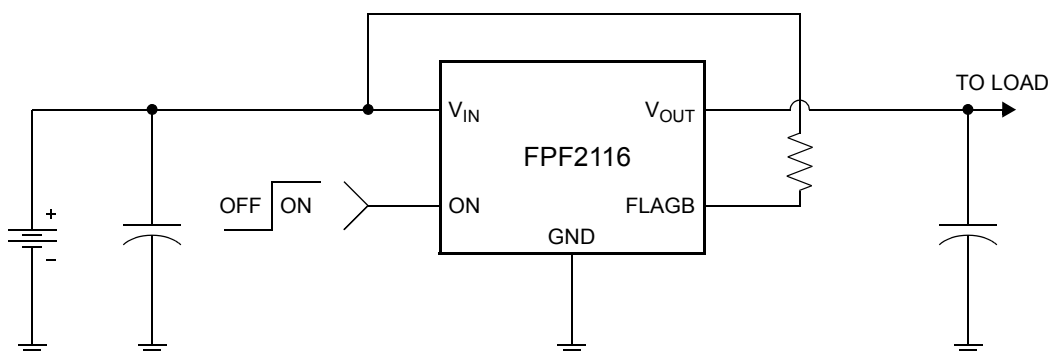
General Description

The FPF2116 is a load switch which provides full protection to systems and loads which may encounter large current conditions. This device contains a 0.125Ω current-limited P-channel MOSFET which can operate over an input voltage range of 1.8-5.5V. Internally, current is prevented from flowing when the MOSFET is off and the output voltage is higher than the input voltage. Switch control is by a logic input (ON) capable of interfacing directly with low voltage control signals. The part contains thermal shutdown protection which shuts off the switch to prevent damage to the part when a continuous over-current condition causes excessive heating.

When the switch current reaches the current limit, the part operates in a constant-current mode to prohibit excessive currents from causing damage. If the constant current condition still persists after 30ms, the part will shut off the switch and pull the fault signal pin (FLAGB) low. An auto-restart feature will turn the switch on again after 480ms if the ON pin is still active. The minimum current limit is 200mA.

The part is available in a space-saving 5 pin SOT23 package.

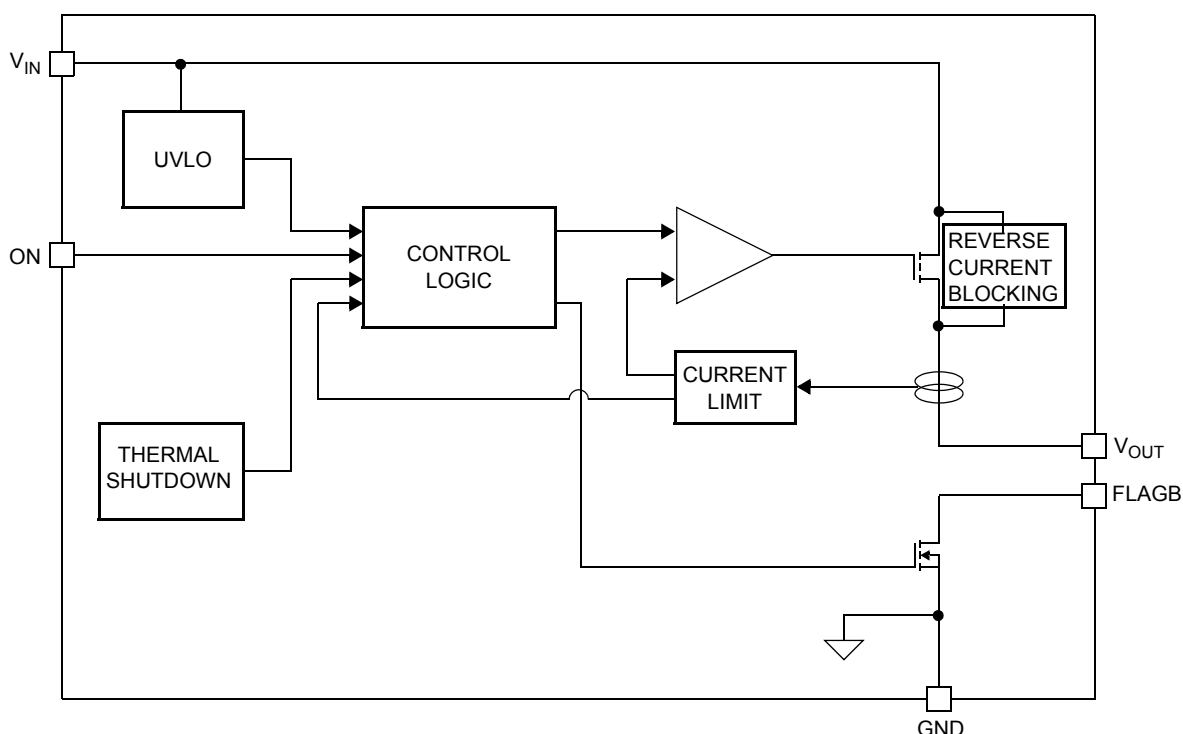
Typical Application Circuit



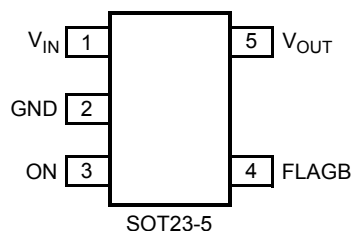
Ordering Information

Part	Current Limit [mA]	Current Limit Blanking Time [ms]	Auto-Restart Time [ms]	ON Pin Activity	Top Mark
FPF2116	200	30	480	Active HI	2116

Functional Block Diagram



Pin Configuration



Pin Description

Pin	Name	Function
1	V _{IN}	Supply Input: Input to the power switch and the supply voltage for the IC
2	GND	Ground
3	ON	ON Control Input
4	FLAGB	Fault Output: Active LO, open drain output which indicates an over current supply, under voltage or over temperature state.
5	V _{OUT}	Switch Output: Output of the power switch

Absolute Maximum Ratings

Parameter	Min	Max	Unit
V_{IN} , V_{OUT} , ON, FLAGB to GND	-0.3	6	V
Power Dissipation @ $T_A = 25^\circ\text{C}$ (note 1)		667	mW
Operating Junction Temperature	-40	125	$^\circ\text{C}$
Storage Temperature	-65	150	$^\circ\text{C}$
Thermal Resistance, Junction to Ambient		150	$^\circ\text{C/W}$
Electrostatic Discharge Protection	HBM	4000	V
	MM	400	V

Recommended Operating Range

Parameter	Min	Max	Unit
V_{IN}	1.8	5.5	V
Ambient Operating Temperature, T_A	-40	85	$^\circ\text{C}$

Electrical Characteristics

$V_{IN} = 1.8$ to 5.5V , $T_A = -40$ to $+85^\circ\text{C}$ unless otherwise noted. Typical values are at $V_{IN} = 3.3\text{V}$ and $T_A = 25^\circ\text{C}$.

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Basic Operation						
Operating Voltage	V_{IN}		1.8		5.5	V
Quiescent Current	I_Q	$I_{OUT} = 0\text{mA}$	$V_{IN} = 1.8$ to 3.3V		95	μA
			$V_{IN} = 3.3$ to 5.5V		110	
V_{IN} Shutdown Current		$V_{ON} = 0\text{V}$, $V_{IN} = 5.5\text{V}$, V_{OUT} short to GND			2	μA
V_{OUT} Shutdown Current		$V_{ON} = 0\text{V}$, $V_{OUT} = 5.5\text{V}$, V_{IN} short to GND			2	μA
On-Resistance	R_{ON}	$V_{IN} = 3.3\text{V}$, $I_{OUT} = 50\text{mA}$, $T_A = 25^\circ\text{C}$		125	160	$\text{m}\Omega$
		$V_{IN} = 3.3\text{V}$, $I_{OUT} = 50\text{mA}$, $T_A = 85^\circ\text{C}$		150	200	
		$V_{IN} = 3.3\text{V}$, $I_{OUT} = 50\text{mA}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	65		200	
ON Input Logic High Voltage (ON)	V_{IH}	$V_{IN} = 1.8\text{V}$	0.75			V
		$V_{IN} = 5.5\text{V}$	1.30			
ON Input Logic Low Voltage	V_{IL}	$V_{IN} = 1.8\text{V}$			0.5	V
		$V_{IN} = 5.5\text{V}$			1.0	
ON Input Leakage		$V_{ON} = V_{IN}$ or GND			1	μA
Off Switch Leakage	I_{SWOFF}	$V_{ON} = 0\text{V}$, $V_{OUT} = 0\text{V}$			1	μA
FLAGB Output Logic Low Voltage		$V_{IN} = 5\text{V}$, $I_{SINK} = 10\text{mA}$		0.1	0.2	V
		$V_{IN} = 1.8\text{V}$, $I_{SINK} = 10\text{mA}$		0.15	0.3	
FLAGB Output High Leakage Current		$V_{IN} = 5\text{V}$, Switch on			1	μA
Protections						
Current Limit	I_{LIM}	$V_{IN} = 3.3\text{V}$, $V_{OUT} = 3.0\text{V}$	200	300	400	mA
Thermal Shutdown		Shutdown Threshold		140		$^\circ\text{C}$
		Return from Shutdown		130		
		Hysteresis		10		
Under Voltage Shutdown	UVLO	V_{IN} Increasing	1.5	1.6	1.7	V
Under Voltage Shutdown Hysteresis				50		mV

Electrical Characteristics Cont.

$V_{IN} = 1.8$ to $5.5V$, $T_A = -40$ to $+85^{\circ}C$ unless otherwise noted. Typical values are at $V_{IN} = 3.3V$ and $T_A = 25^{\circ}C$.

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Dynamic						
Turn On Time	t_{ON}	$R_L = 500\Omega$, $C_L = 0.1\mu F$		25		μs
Turn Off Time	t_{OFF}	$R_L = 500\Omega$, $C_L = 0.1\mu F$		50		μs
V_{OUT} Rise Time	t_{RISE}	$R_L = 500\Omega$, $C_L = 0.1\mu F$		12		μs
V_{OUT} Fall Time	t_{FALL}	$R_L = 500\Omega$, $C_L = 0.1\mu F$		120		μs
Over Current Blanking Time	t_{BLANK}		15	30	60	ms
Auto-Restart Time	$t_{RESTART}$		240	480	960	ms
Short Circuit Response Time		$V_{IN} = V_{ON} = 3.3V$. Moderate Over-Current Condition.		3		μs
		$V_{IN} = V_{ON} = 3.3V$. Hard Short.		20		ns

Note 1: Package power dissipation on 1square inch pad, 2 oz copper board.

Typical Characteristics

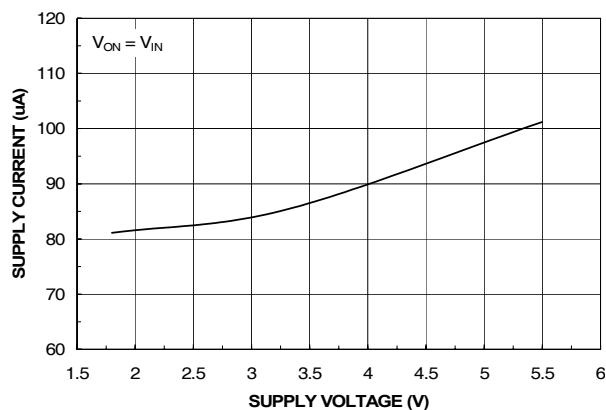


Figure 1. Quiescent Current vs. Input Voltage

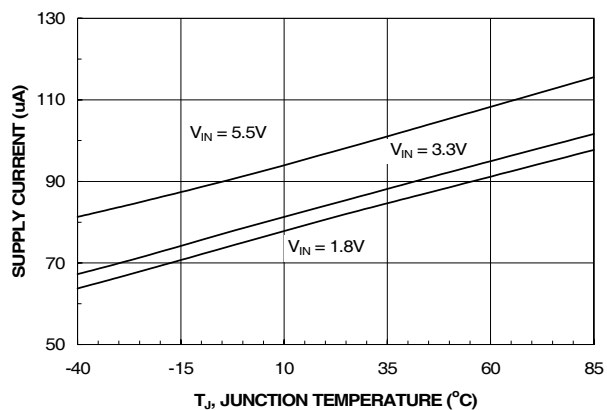


Figure 2. Quiescent Current vs. Temperature

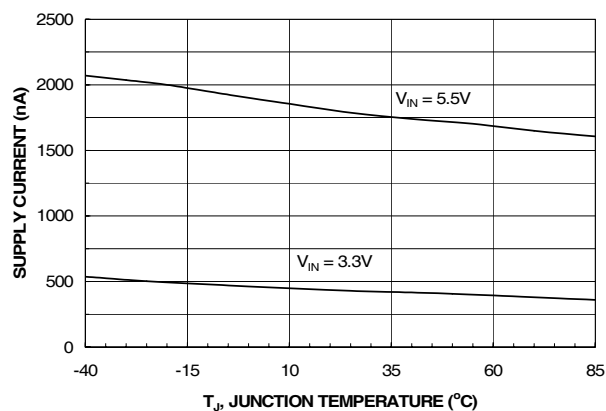


Figure 3. I_{SHUTDOWN} Current vs. Temperature

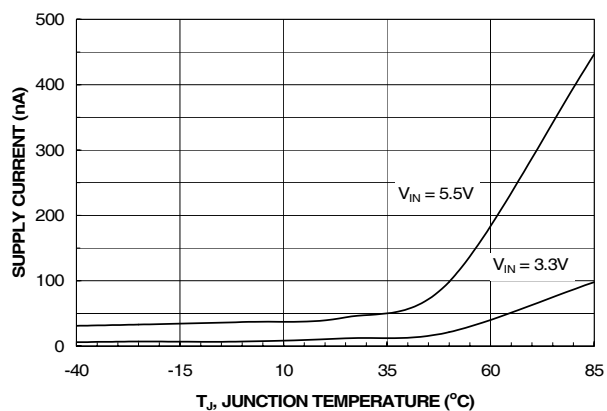


Figure 4. I_{SWITCH-OFF} Current vs. Temperature

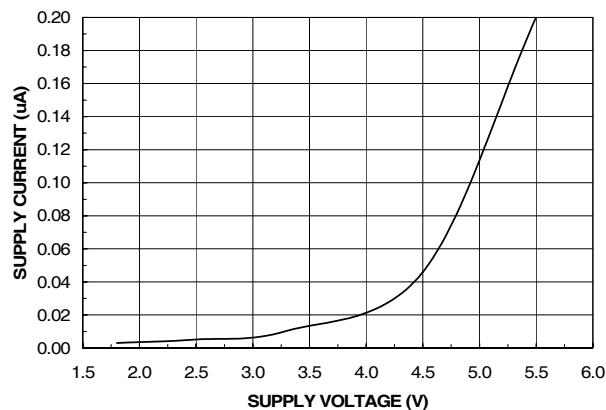


Figure 5. Reverse Current vs. Output Voltage

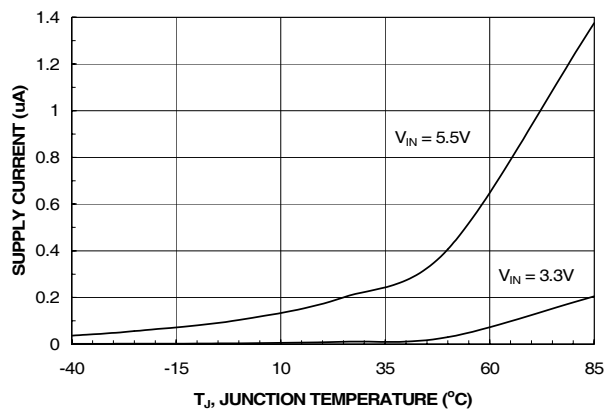


Figure 6. Reverse Current vs. Temperature

Typical Characteristics

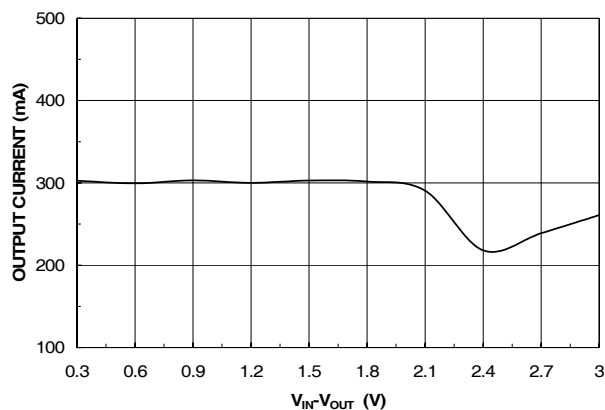


Figure 7. Current Limit vs. Output Voltage

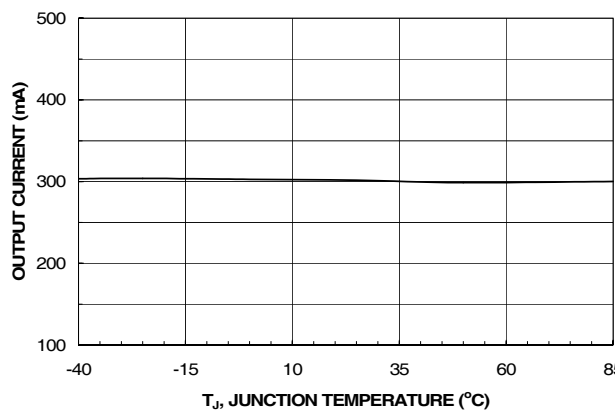


Figure 8. Current Limit vs. Temperature

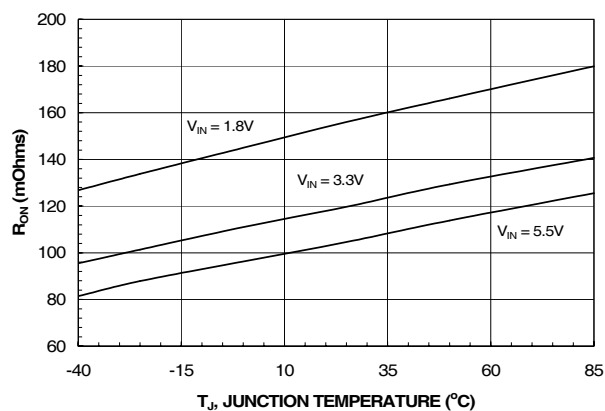


Figure 9. R_{ON} vs. Temperature

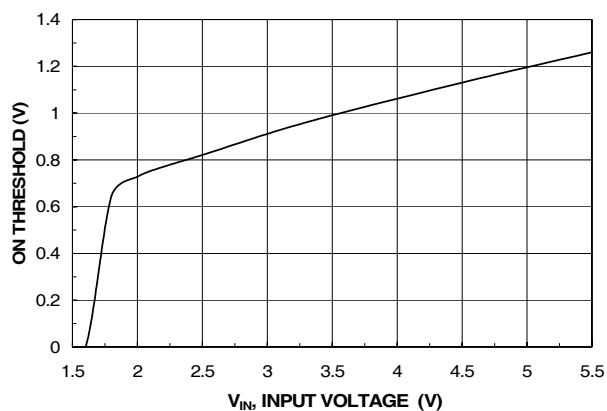


Figure 10. On Threshold vs. V_{IN}

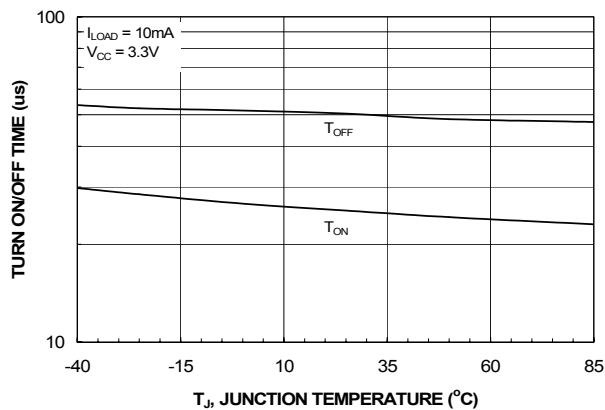


Figure 11. T_{ON}/T_{OFF} vs. Temperature

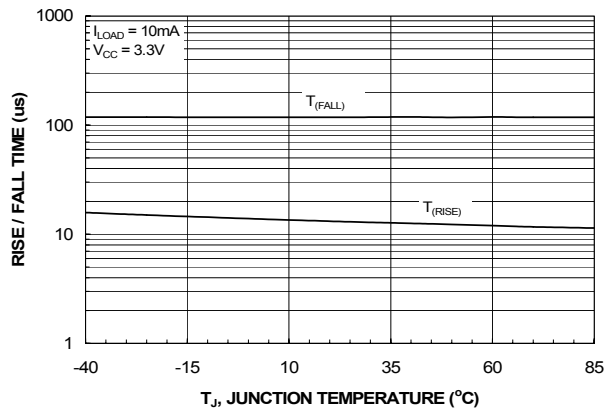


Figure 12. T_{RISE}/T_{FALL} vs. Temperature

Typical Characteristics

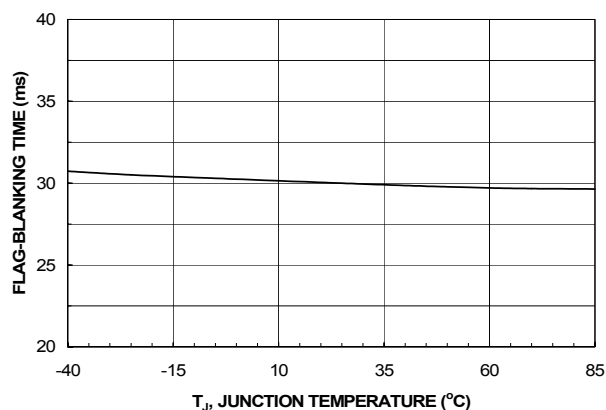


Figure 13. T_{BLANK} vs. Temperature

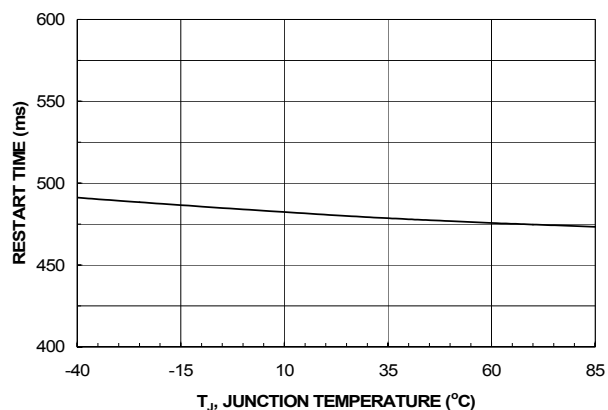


Figure 14. $T_{RESTART}$ vs. Temperature

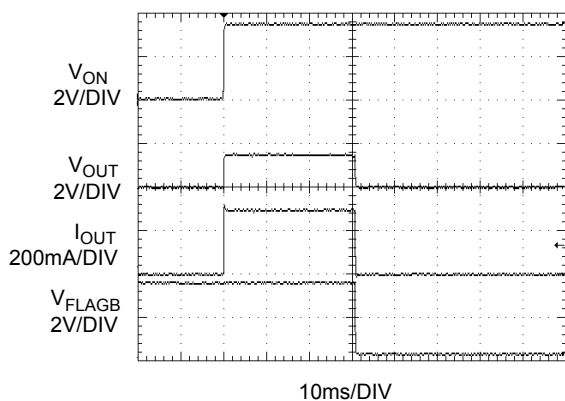


Figure 15. T_{BLANK} Response

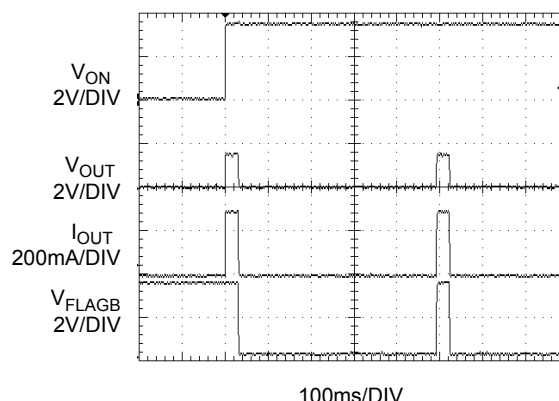


Figure 16. $T_{RESTART}$ Response

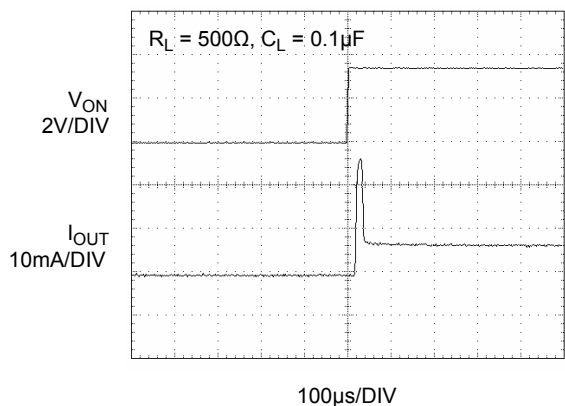


Figure 17. T_{ON} Response

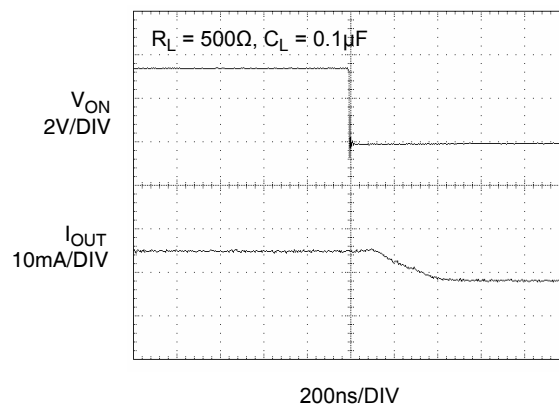


Figure 18. T_{OFF} Response

Typical Characteristics

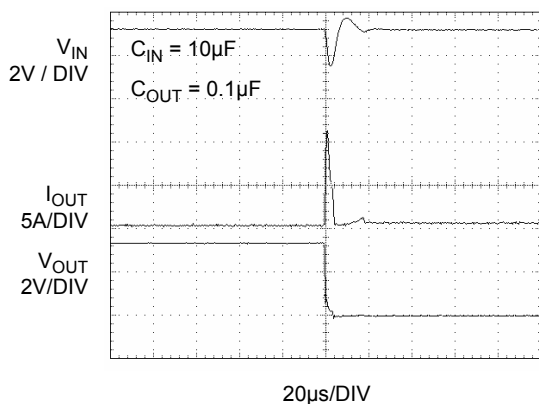


Figure 19. Short Circuit Response Time
(Output Shorted to GND)

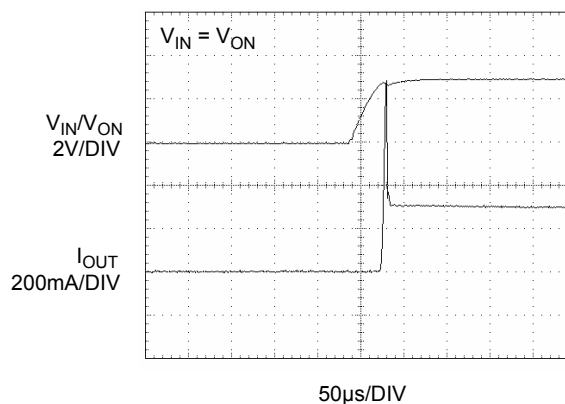


Figure 20. Current Limit Response
(Switch power up to hard short)

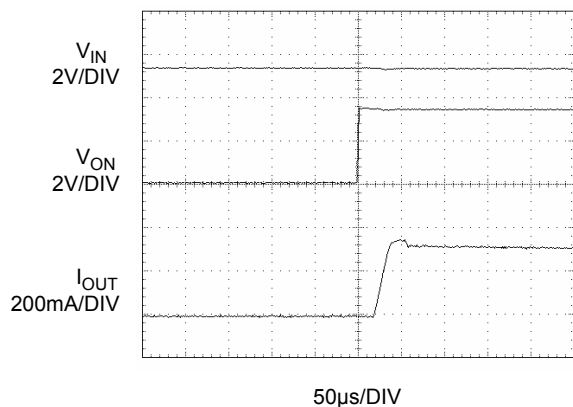


Figure 21. Current Limit Response Time
(Output Shorted to GND by 10Ω, moderate short)

Description of Operation

The FPF2116 is a current limited switch that protects systems and loads which can be damaged or disrupted by the application of high currents. The core of the device is a 0.125Ω P-channel MOSFET and a controller capable of functioning over a wide input operating range of 1.8-5.5V. The controller protects against system malfunctions through current limiting, under-voltage lockout and thermal shutdown. The current limit is preset for 200mA.

On/Off Control

The ON pin controls the state of the switch. Activating ON continuously holds the switch in the on state so long as there is no fault. An under-voltage on V_{IN} or a junction temperature in excess of 150°C overrides the ON control to turn off the switch. In addition, excessive current will cause the switch to turn off. The part has an Auto-Restart feature which will automatically turn the switch on again after 480 ms. ON is active HI and has a low threshold making it capable of interfacing with low voltage signals. When the MOSFET is off, the body diode is disabled so no current can flow through it.

Fault Reporting

Upon the detection of an over-current, an input under-voltage, or an over-temperature condition, the FLAGB signals the fault mode by immediately activating LO. The FLAGB goes LO at the end of the blanking time. It will remain LO during the fault and immediately returns HI at the end of the fault condition. FLAGB is an open-drain MOSFET which requires a pull-up resistor between V_{IN} and FLAGB. During shutdown, the pull-down on FLAGB is disabled to reduce current draw from the supply.

Current Limiting

The current limit ensures that the current through the switch doesn't exceed 400mA while not limiting at less than 200mA. The part has a blanking time of 30 ms, nominally, during which the switch will act as a constant current source. At the end of the blanking time, the switch will be turned-off and the FLAGB pin will activate to indicate that current limiting has occurred.

Under-Voltage Lockout

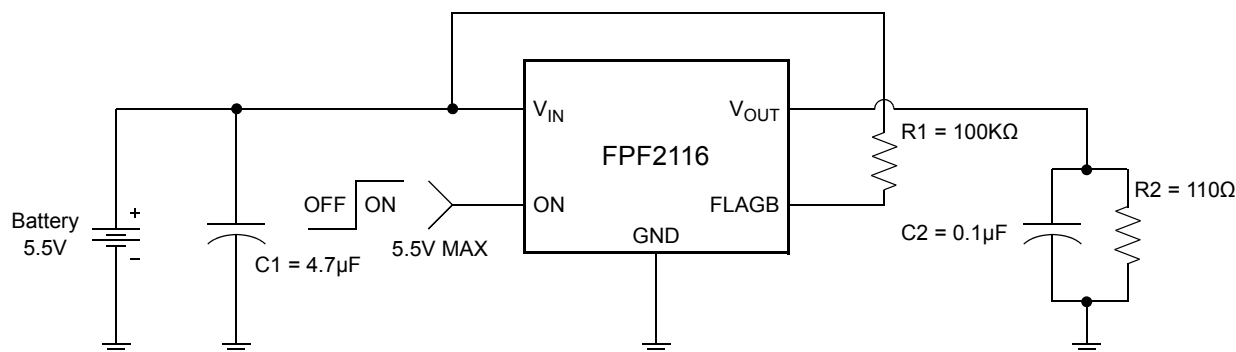
The under-voltage lockout turns-off the switch if the input voltage drops below the under-voltage lockout threshold. With the ON pin active the input voltage rising above the under-voltage lockout threshold will cause a controlled turn-on of the switch which limits current over-shoots.

Thermal Shutdown

The thermal shutdown protects the part from internally or externally generated excessive temperatures. During an over-temperature condition the FLAGB is activated and the switch is turned-off. The switch automatically turns-on again if temperature of the die drops below the threshold temperature.

Application Information

Typical Application



Input Capacitor

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns-on into a discharged load capacitor or a short-circuit, a capacitor needs to be placed between V_{IN} and GND. A $4.7\mu\text{F}$ ceramic capacitor, C_{IN} , must be placed close to the V_{IN} pin. A higher value of C_{IN} can be used to further reduce the voltage drop experienced as the switch is turned on into a large capacitive load.

Board Layout

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal and short-circuit operation. Using wide traces for V_{IN} , V_{OUT} and GND will help minimize parasitic electrical effects along with minimizing the case to ambient thermal impedance.

Output Capacitor

A $0.1\mu\text{F}$ capacitor C_{OUT} , should be placed between V_{OUT} and GND. This capacitor will prevent parasitic board inductances from forcing V_{OUT} below GND when the switch turns-off. The total output capacitance needs to be kept below a maximum value, $C_{OUT(max)}$, to prevent the part from registering an over-current condition and turning off the switch. The maximum output capacitance can be determined from the following formula,

$$C_{OUT(max)} = \frac{I_{LIM(min)} \times t_{BLANK(min)}}{V_{IN}} \quad (1)$$

Power Dissipation

During normal operation as a switch, the power dissipation is small and has little effect on the operating temperature of the part. The parts with the higher current limits will dissipate the most power and that will only be,

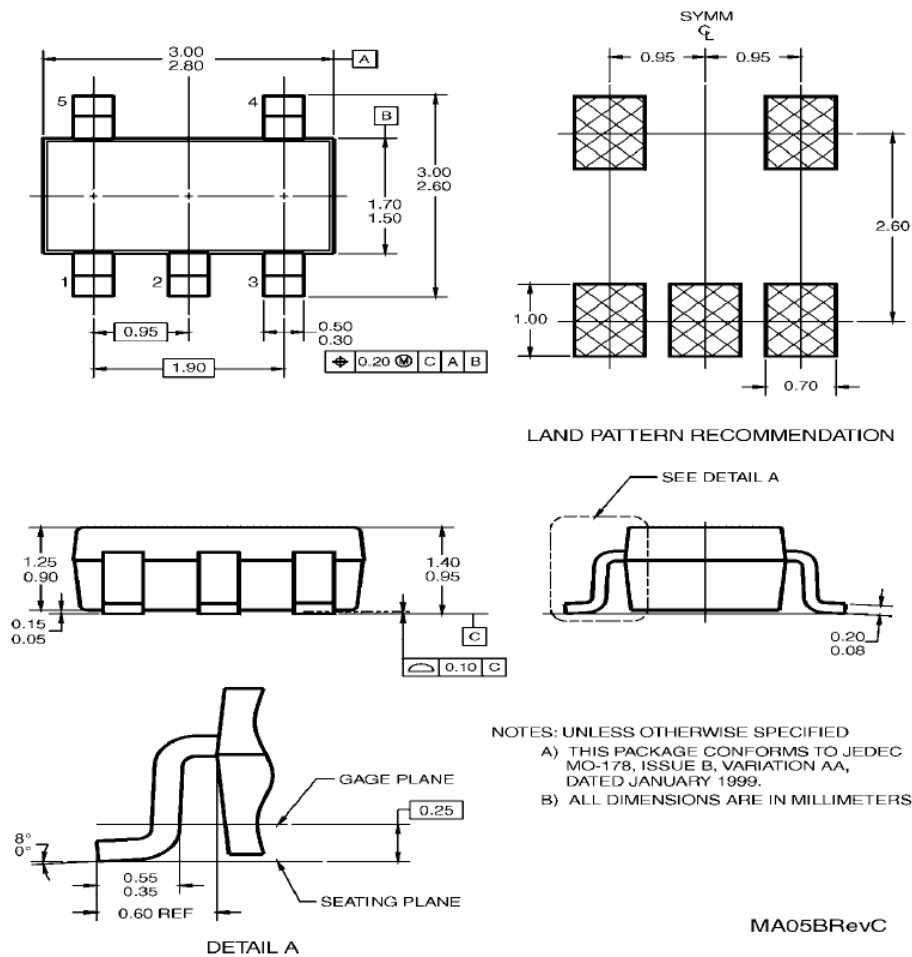
$$P = (I_{LIM})^2 \times R_{DS} = (0.4)^2 \times 0.125 = 20\text{mW} \quad (2)$$

When in current limit the maximum power dissipation will occur when the output is shorted to ground. The power dissipation will scale by the Auto-Restart Time, t_{RSTR} , and the Over Current Blanking Time, t_{BLANK} , so that the maximum power dissipated is typically,

$$\begin{aligned} P(max) &= \frac{t_{BLANK}}{t_{RETRY} + t_{BLANK}} \times V_{IN(max)} \times I_{LIM(max)} \\ &= \frac{60}{60 + 960} \times 5.5 \times 0.4 = 130\text{mW} \end{aligned} \quad (3)$$

Dimensional Outline and Pad Layout

Package MA05B



DETAIL A

5-Lead SOT23, JEDEC MO-178, 1.6mm
 Package Number MA05B




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Definition of Terms

Datasheet Identification	Product Status	Definition
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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